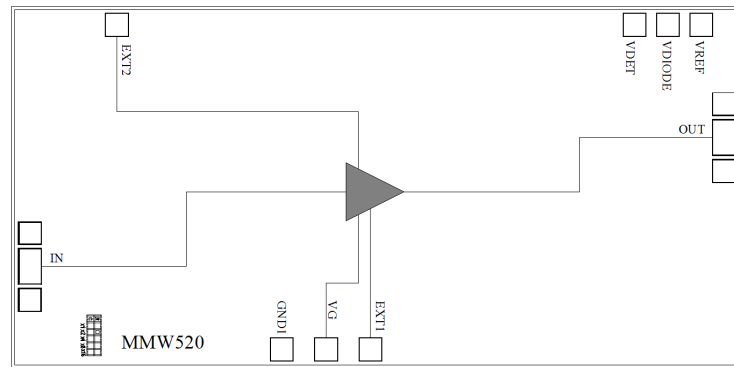




Features

- Frequency: DC-30GHz
- Small Signal Gain: 17dB Typical
- Gain Flatness: ± 1.0 dB Typical
- Noise Figure: 2.5dB Typical
- Psat: 28dBm Typical @ +12V/-0.5V
- Supply voltage:
 - VD =+12V
 - VG=-0.5V
- Input/Output: 50 Ω
- Die Size: 3.3 x 1.63 x 0.1mm

Functional Block Diagram



Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

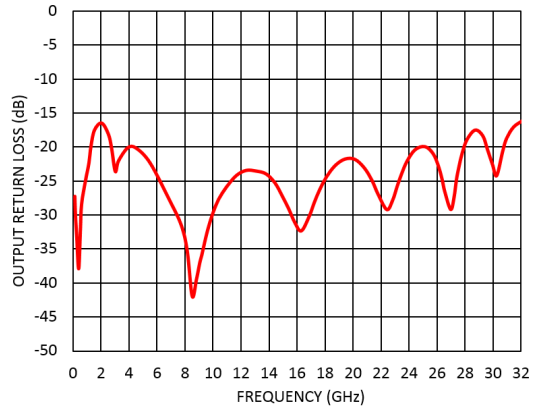
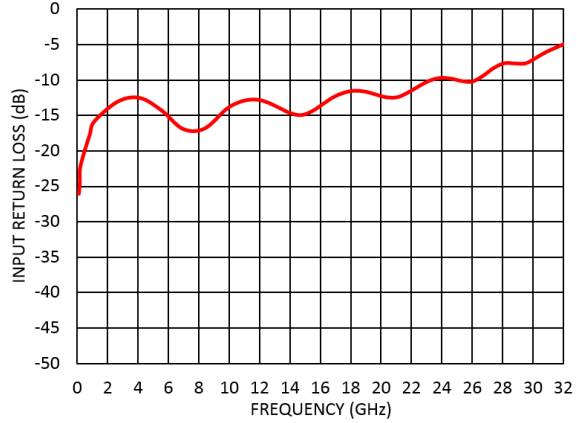
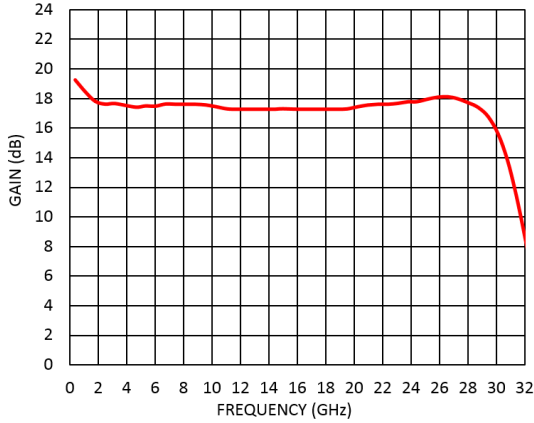
Electrical Specifications

TA = +25°C, VD=+12V, VG= -0.5V IDD = 226mA Typical

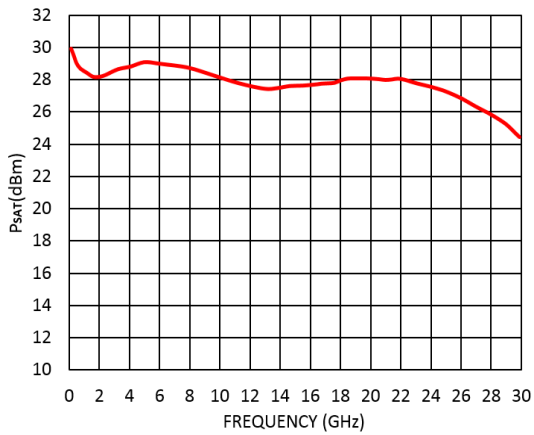
Parameters	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency	DC		10	10		30	GHz
Small Signal Gain	16	17		15	16.5		dB
Gain Flatness		± 1.0			± 1.0		dB
Noise Figure		2.5			5		dB
P1dB - Output 1dB Compression		26			24		dBm
Psat - Saturated Output Power		28			27		dBm
Input Return Loss		13			10		dB
Output Return Loss		18			18		dB
* Adjust VG slightly to obtain device current of 226 mA.							



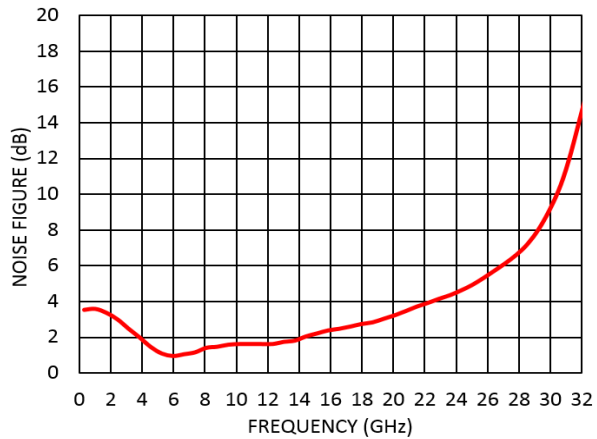
Measurement Plots: S-parameters



Measurement Plots: PSAT



Measurement Plots: Noise Figure





Absolute Maximum Ratings

Drain Bias Voltage (VD)	+14V
Gate Bias Voltages(VG)	-1 to 0 V
RF Input Power (RFIN)@(+12V)	+17dBm
Channel Temperature	175 °C
Continuous Pdiss (T = 85 °C) (derate 40mW/°C above 85 °C)	3.6W
Thermal Resistance (channel to die bottom)	50°C/W
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150 °C

Typical Supply Current vs. VD,VG

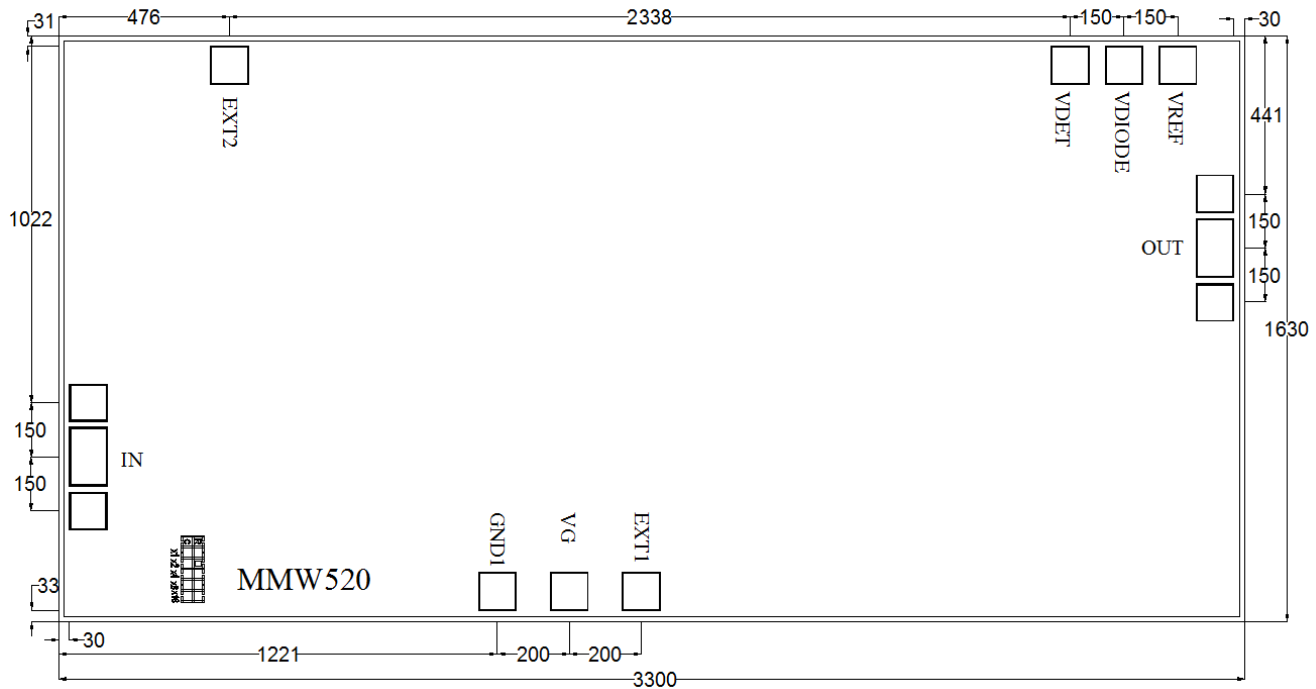
VD (V)	VG (V)	IDD (mA)
12	-0.5	226



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS



Outline Drawing: All Dimensions in μm

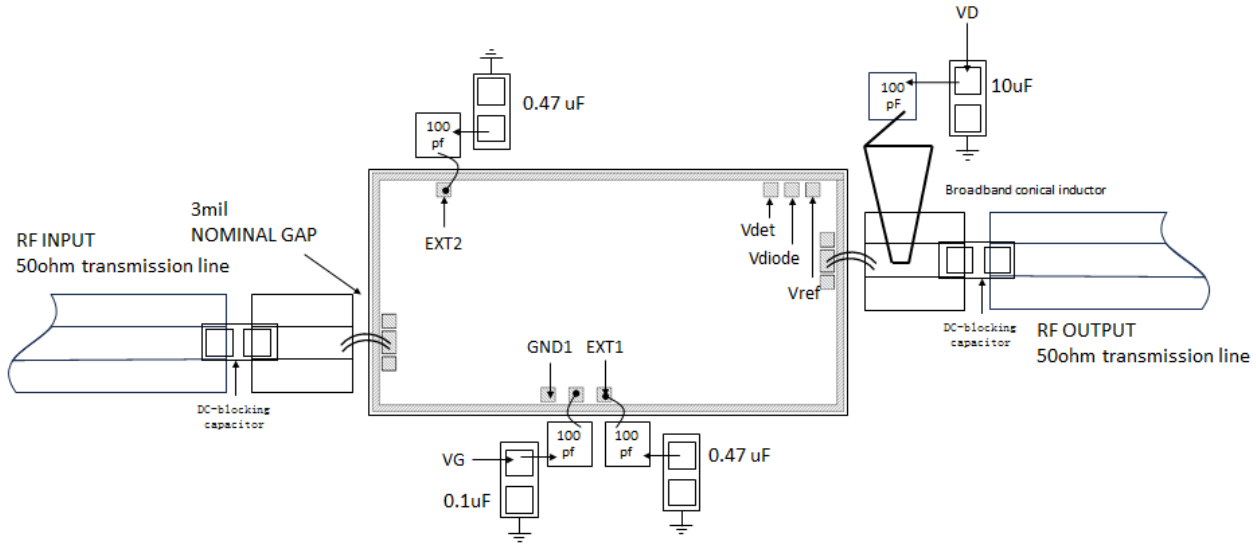


Notes:

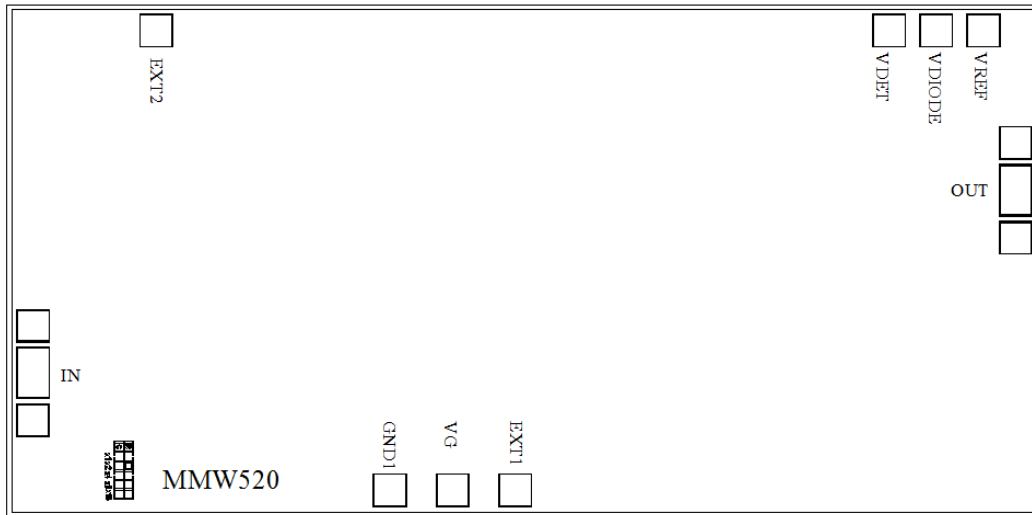
1. Die thickness: 100 μm
2. DC bond pad is 100*100 μm^2
3. RF IN/OUT bond pad is 100*100 μm^2
4. Bond pad metalization: Gold
5. Backside metalization: Gold



Assembly Drawing



No.	Mnemonic	Description
1	RF IN	Signal input terminal, connected to 50Ω circuit; blocking capacitor required.
2	RF OUT	Signal output terminal, connected to 50Ω circuit; blocking capacitor required; external DC biasing network required; drain current provided.
3	VG	Amplifier Gate Controls. External bypass capacitors of 0.1μf and 100pf are required for these pads. ESD protection diodes are included and turn on below -1.0 V.
4	EXT1	External bypass pad; connect to external 100pf and 0.47uf bypass capacitor.
5	EXT2	External bypass pad; connect to external 100pf and 0.47uf bypass capacitor.
6	Vref	Detector ref
7	Vdiode	Detector bias
8	Vdet	Detector output
9	Die Bottom	Die bottom must be connected to RF and dc ground.



Biasing and Operation

Turn ON procedure:

1. Connect GND to RF and dc ground.
2. Set the gate bias voltages, VG1 to $-1.0V$.
3. Set the drain bias voltages VD to $+12V$.
4. Increase the gate bias voltages to achieve a quiescent supply current of 226 mA.
5. Apply RF signal.

Turn OFF procedure:

1. Turn off the RF signal.
2. Decrease the gate bias voltages, VG1 to $-1.0V$ to achieve a $I_{DQ} = 0$ mA (approximately).
3. Decrease the drain bias voltages to 0 V.
4. Increase the all gate bias voltages to 0 V.

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